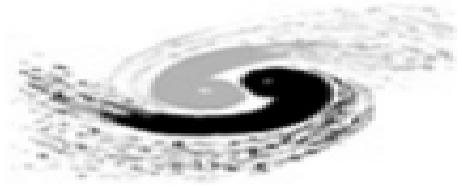


Automatic High-Granularity Timing Detector Module Assembly with Gantry System



Hao Zeng

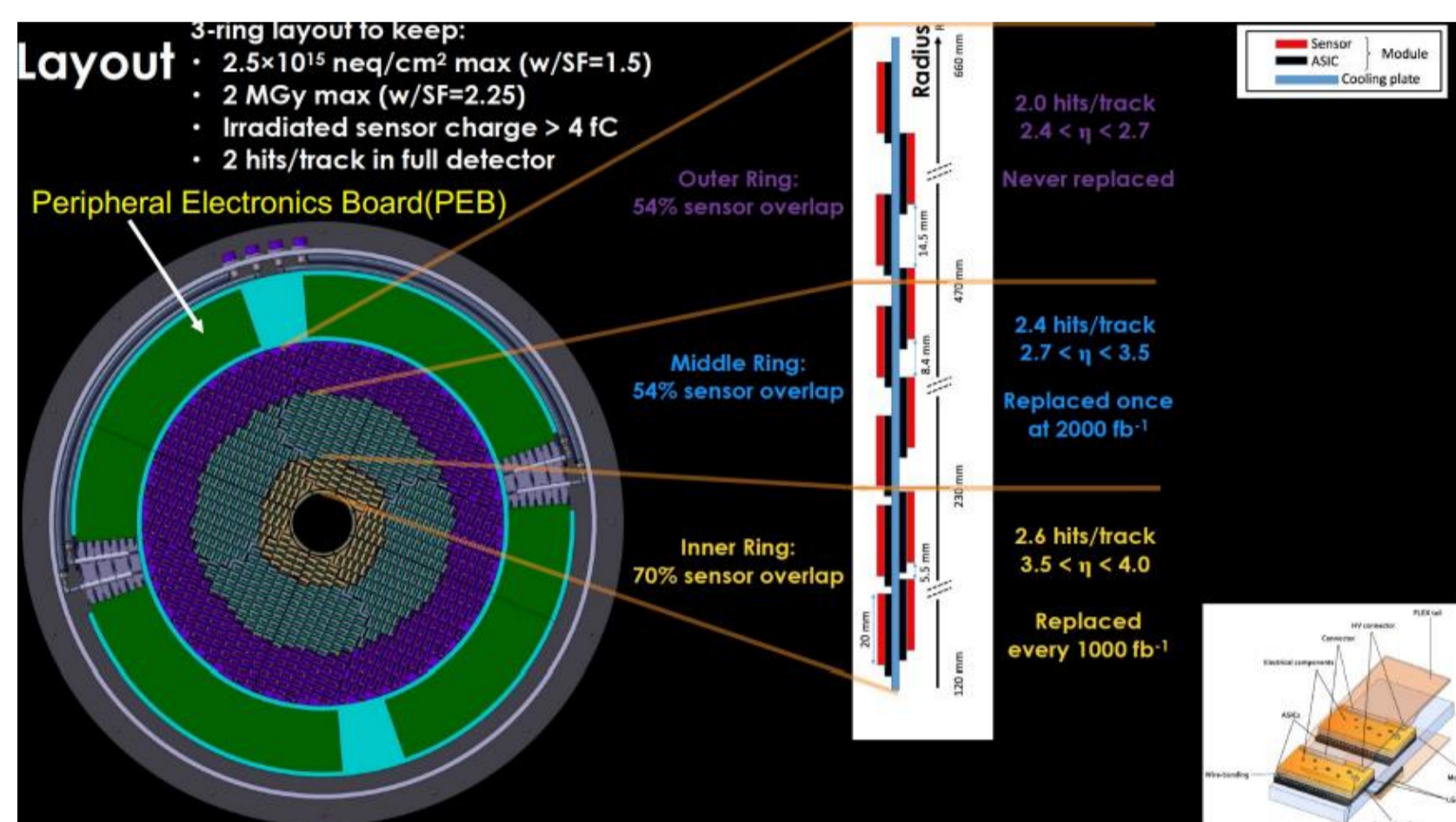
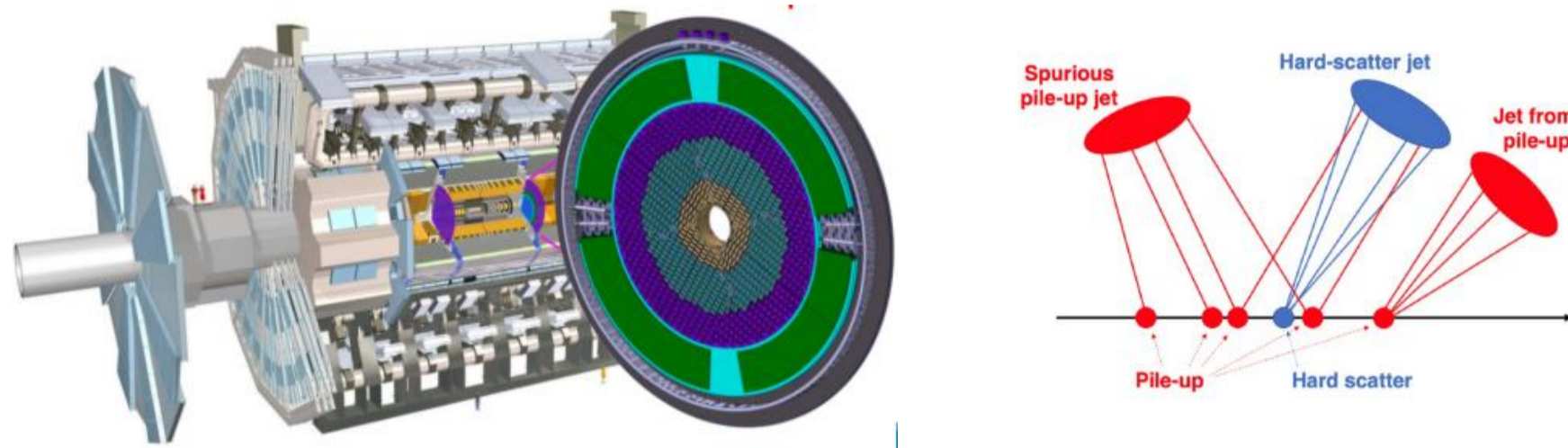
Institute of High Energy Physics, CAS, Beijing, China



Introduction

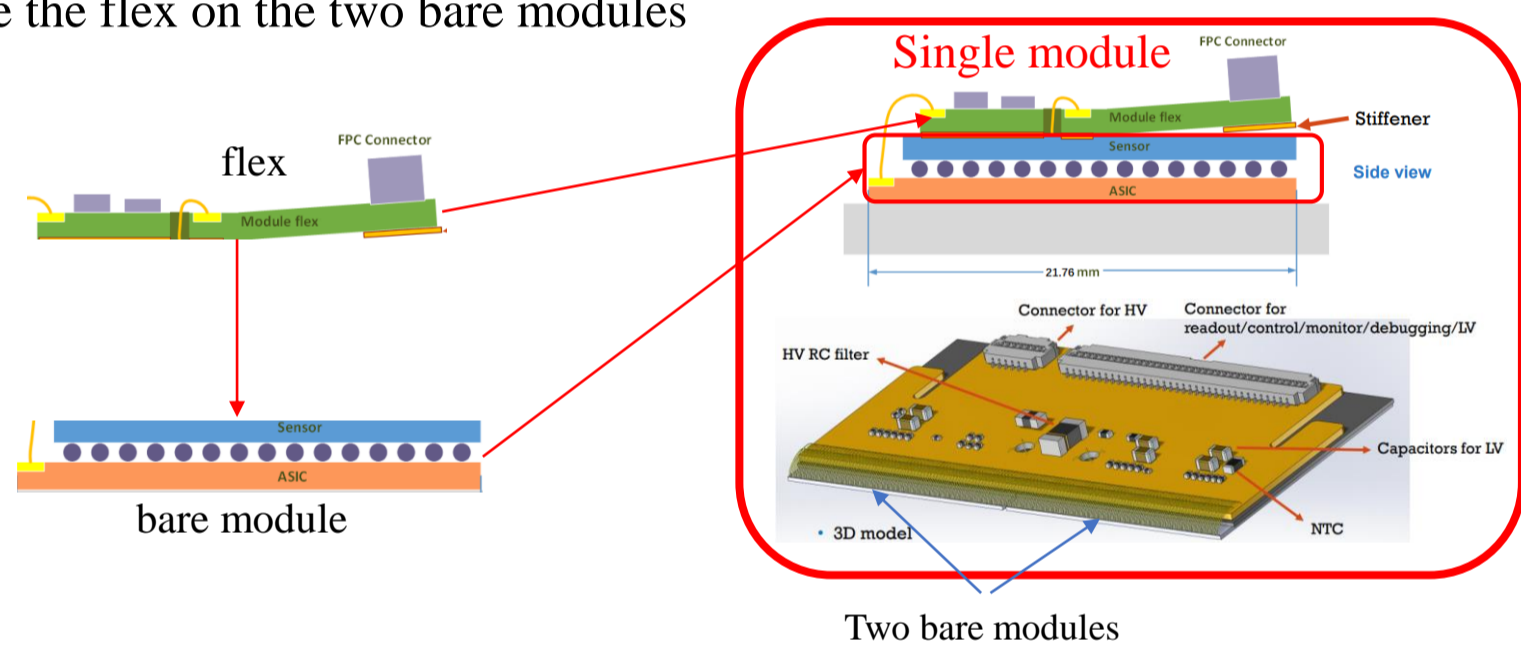
High Granularity Timing Detector (HGTD)

- HGTD aim to reduce pileup contribution at HL-LHC
 - Timing resolution is required to be better than 50ps
 - 6.4m² area silicon detector and ~ 3.6 × 10⁶ channels
 - High Granularity: Pixel pad size: 1.3mm × 1.3mm
 - Radiation hardness: 2.5 × 10¹⁵ N_{eq}/cm² and 2MGy
- About 3000 modules are planned to be assembled at IHEP
- Automation assembly with robotic gantry system is the best choice due to its high positioning precision and assembly rate.

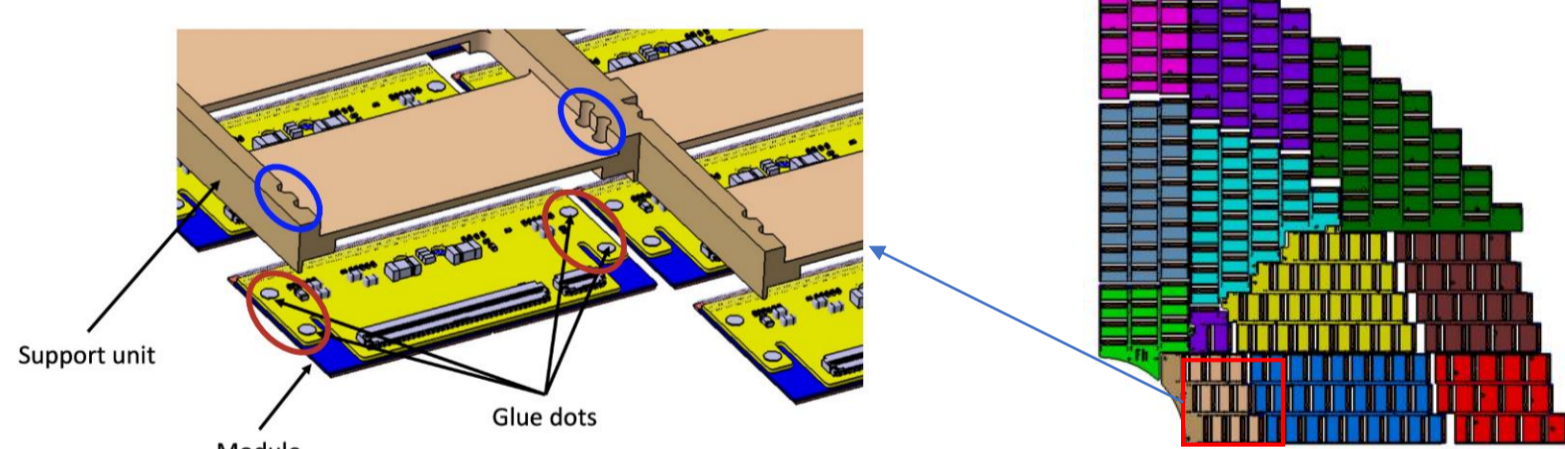


Task of the HGTD module assembly with gantry system

- Glue the flex on the two bare modules



- Glue the module on the support units



- Specification of the module mass and dimension

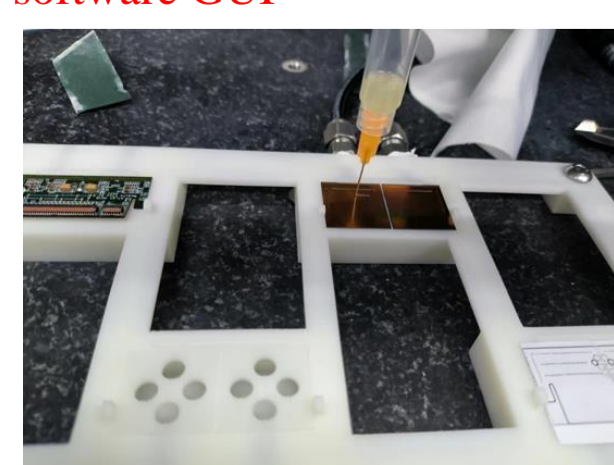
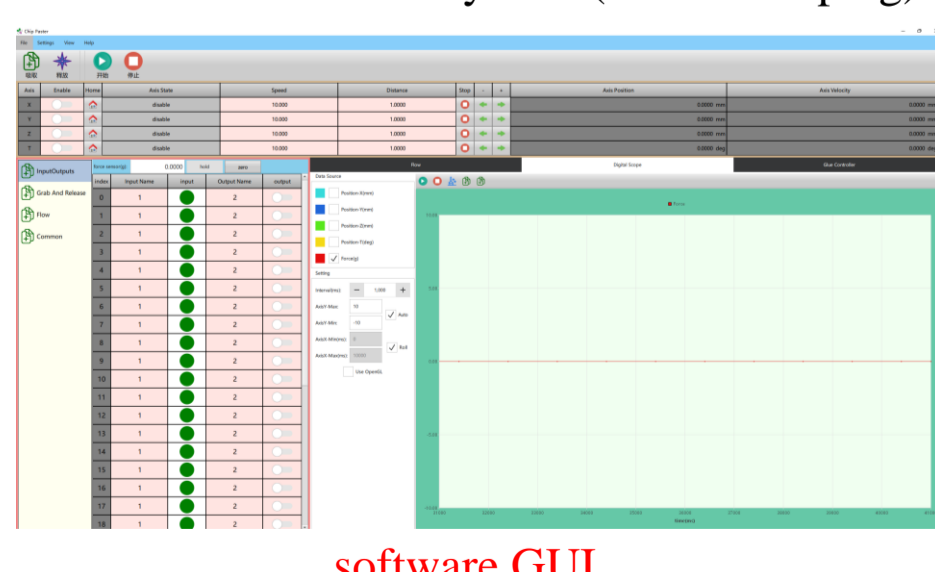
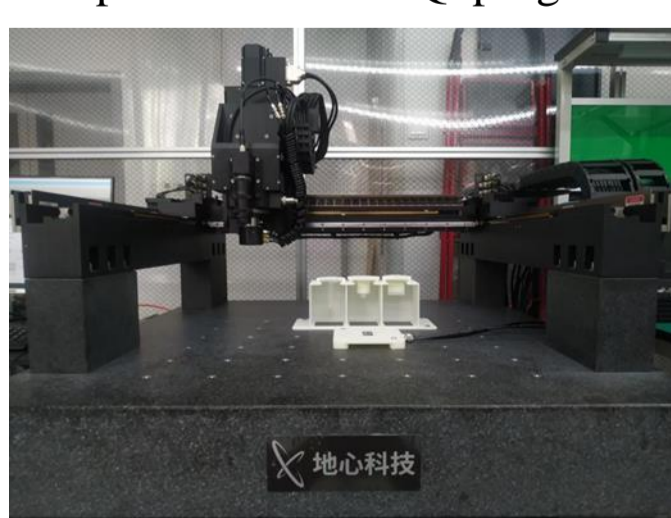
Module weight: 3.0 g	Nominal thickness of the module: 2.52 mm
Maximum thickness of the module: 3.32 mm	Maximum width of the module: 40.6 mm
Nominal gap between two bare modules: 200 μm	Minimum gap between two bare modules: 50 μm

- Specifications on the module flex to bare module attachment

Glue thickness	50±30μm
Single lap shear force	>2N
Total coverage of glue area	80%, no spillage
Alignment between module flex and bare modules	< 100μm displacement, < 0.1° rotation

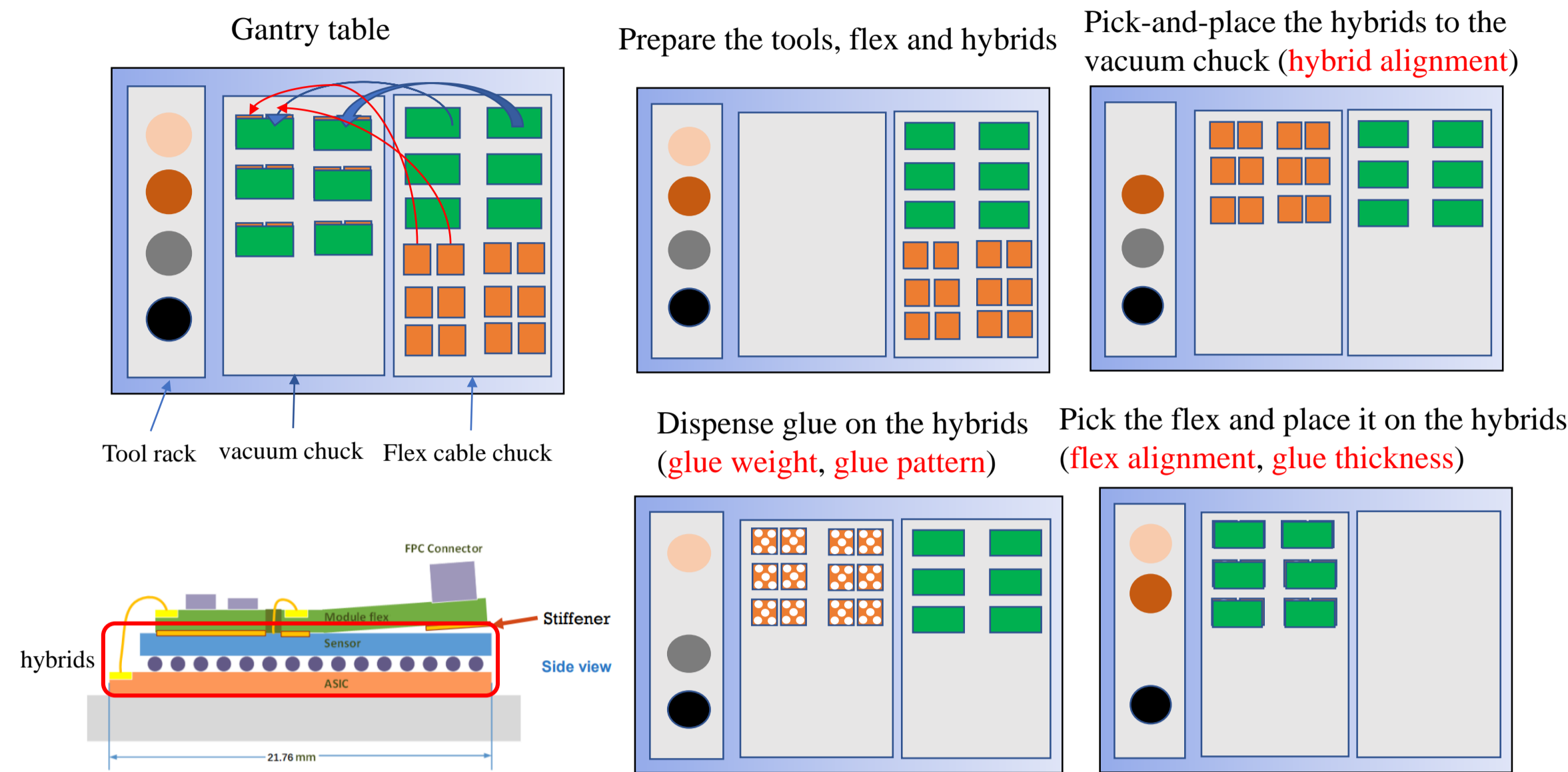
The gantry system at IHEP

- Robotic pick-and-place for systematic module assembly (gantry), consists of:
 - Coretech gantry positioning system with ACS motion controller (500 mm * 500 mm * 150 mm * 340° travel, repositioning resolution ~ 1μm)
 - Integrated with Keyence vision system, pressure sensor, multi-channel electro-valves (maximum 32), Nordson EFD Glue Dispensing controller, flexible vacuum and air pressure piping system, and custom picking and gluing tools
 - Open source C++ Qt program with GUI to control the whole system (still developing)



Automation Assembly Procedures

Gluing of the flex on the bare module



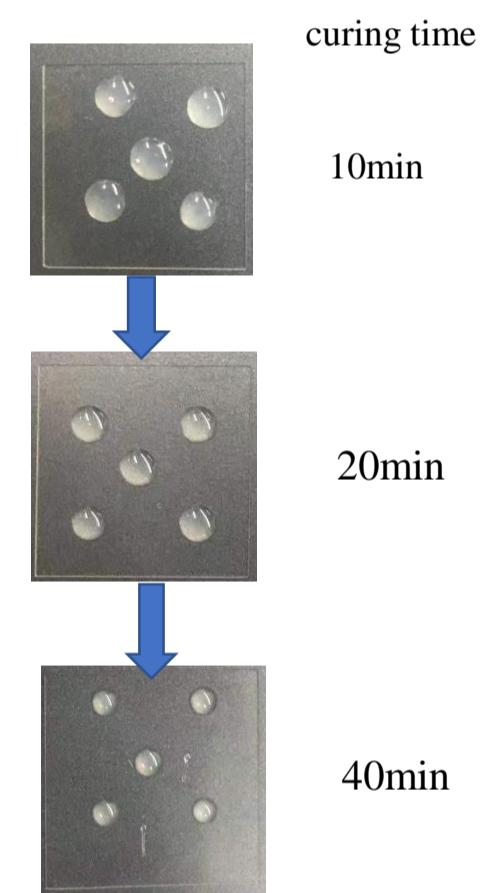
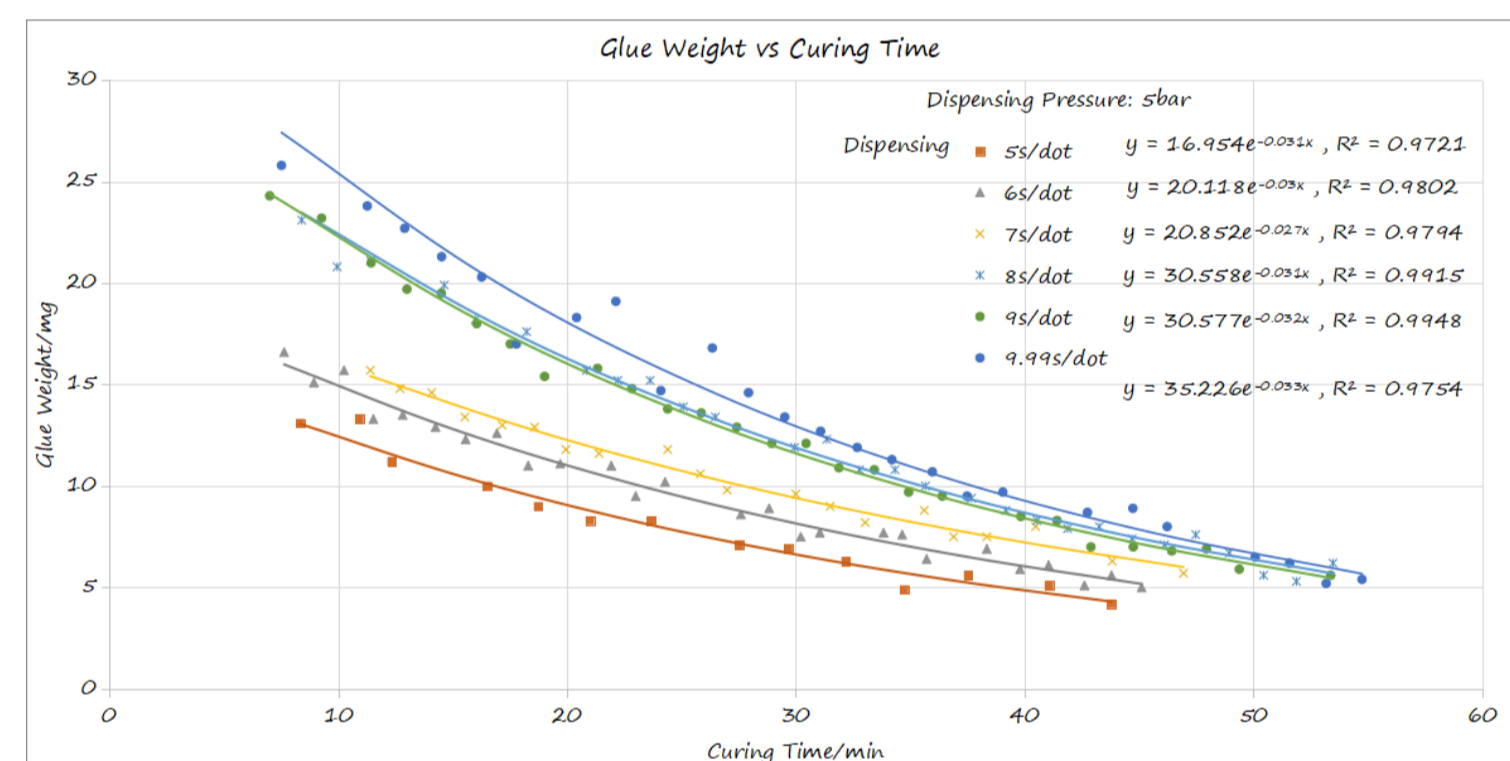
Current status at IHEP

- Gantry system has already been installed with all hardware components in a clean room:
 - Vacuum system, air pressure system and vision system
- Positioning resolution validation was done with laser system (< 1μm)

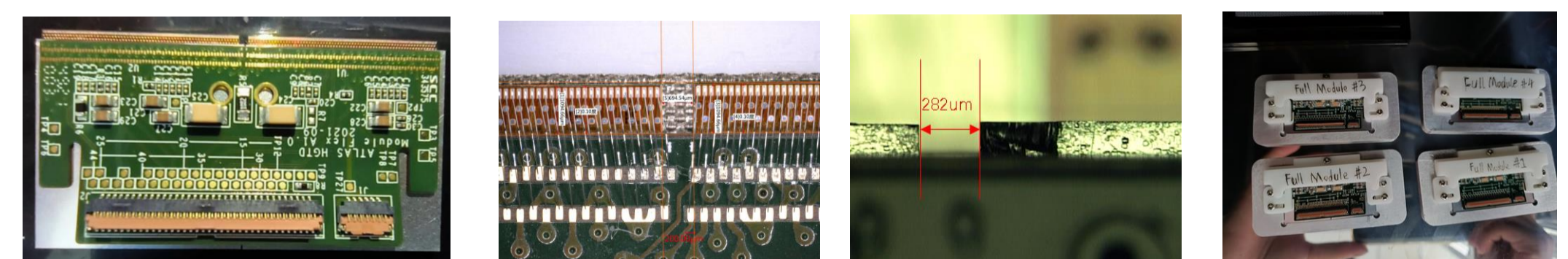
Axis	Calibration interval	Test interval	Specification	Result
X	50mm	500mm	3μm	1μm
Y	50mm	500mm	3μm	0.4μm
Z	15mm	150mm	0.8μm	0.8μm
Theta	15°	360°	5arc sec	2.074arc sec

- Glue dispensing function is integrated

- Glue weight measurement depending on the pressure and curing time has been done using the integration software



- Several digital module and full module has been assembled using the gantry and custom tooling
 - Wire-bonding was performed successful
 - The metrology results are very close the specifications



	B3B5(mm)	B4B6(mm)	Nominal gap(um)	Average Δ nominal(um)
Full Module 1	0.215	0.200	280	-72
Full Module 2	0.235	0.311	280	-7
Full Module 3	0.157	0.196	280	-104
Full Module 4	0.282	0.285	280	3
Average rotation angle[°]	-0.067	0.128	0.070	-0.182

Summary and outlook

- A high precision positioning gantry system has been built in IHEP for automatic HGTD module assembly
- We performed basic testing for the gantry, it satisfied the module assembly requirements.
- Software development and custom tooling design have made huge progress.
 - Gluing dispensing integration
 - Fully 3D-printed tooling
- Several HGTD full modules has been assembled using the gantry system and the metrology results of these modules are very close to the HGTD module specification.
- Outlook:
 - Machining tooling design is on-going for better glue thickness flatness control
 - Software integration with pattern recognition using the CCD camera for better alignment
 - Alignment between two bare modules (hybrids)
 - Alignment between flex and bare module